

EtraLED

EtraLED-BRI-9620 Bridgelux Modular Passive Star LED Heat Sink ϕ 96mm

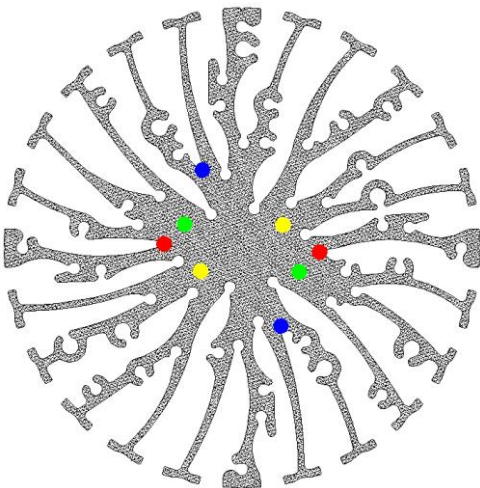
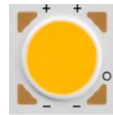
Features VS Benefits

- * The EtraLED-BRI-9620 Bridgelux modular passive star LED heat sink are specifically designed for luminaires using the Bridgelux LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,400 to 3,600 lumen.
- * Thermal resistance range Rth 2.08°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Bridgelux V Series™, Vero® SE Series, Vero® Series, H Series™ and Vesta™ Series LED engines.
- * Diameter 96.0mm - standard height 20.0mm, Other heights on request.
- * Extruded from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Bridgelux COB's and LED modules which standard fit on the srar LED heat sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.



Bridgelux LED Modules directly Mounting Options

Bridgelux V13, V15, LED Array Series:

BXRE-20xxxxxx-x-xx; BXRE-40xxxxxx-x-xx;
 BXRE-27xxxxxx-x-xx; BXRE-50xxxxxx-x-xx;
 BXRE-30xxxxxx-x-xx; BXRE-57xxxxxx-x-xx;
 BXRE-35xxxxxx-x-xx; BXRE-65xxxxxx-x-xx;

With the Zhaga Book 3 Holders:

BJB holder: 47.319.2025.50; 47.319.2030.50;

Direct mounting with machine screws M3x6.5mm, Blue indicator marks.

With the LEDiL products:

Olivia series: FN14637-S;

Ronda series: FN15xxx-xx;

Bridgelux Vero® Series Vero 10, Vero 13 LED Array and Vero® SE Series Vero 10 SE, Vero 13 SE LED Array

BXRC-27xxxx-x-xx; BXRC-50xxxxxx-x-xx;
 BXRC-30xxxx-x-xx; BXRC-57xxxxxx-x-xx;
 BXRC-35xxxx-x-xx; BXRC-65xxxxxx-x-xx;
 BXRC-40xxxx-x-xx;

With the Bridgelux Holder:

Direct mounting with machine screws M3x6.5mm.

Vero 10 for the yellow indicator mark, Vero 13 for the red indicator mark.

With the LEDiL products:

Olivia series: FN14637-S; FN14828-M;

Ronda series: FN15xxx-xx;

Bridgelux® H Series™ H6, H9 LED Array:

BXRH-27xxxx-x-xx; BXRH-35xxxxxx-x-xx;
 BXRH-30xxxx-x-xx; BXRH-40xxxxxx-x-xx;

With the Zhaga Book 11 Holders:

BJB holder: 47.319.6120.50; 47.319.6104.50;

Direct mounting with machine screws M3x6.5mm, Green indicator marks.

With the LEDiL products: Ronda series: FN15xxx-xx;

Bridgelux® Vesta™ Series Dim-To-Warm 9mm Array

BXRV-DR-1830H-1000-x-13;

With the Zhaga Book 11 Holders:

BJB holder: 47.319.6180.50;

Direct mounting with machine screws M3x6.5mm, Green indicator marks.

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Mounting Options and Drawings & Dimensions

Example: EtraLED-BRI-9620-B-1,2

Example: EtraLED-BRI-96 **1** - **2** - **3**

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

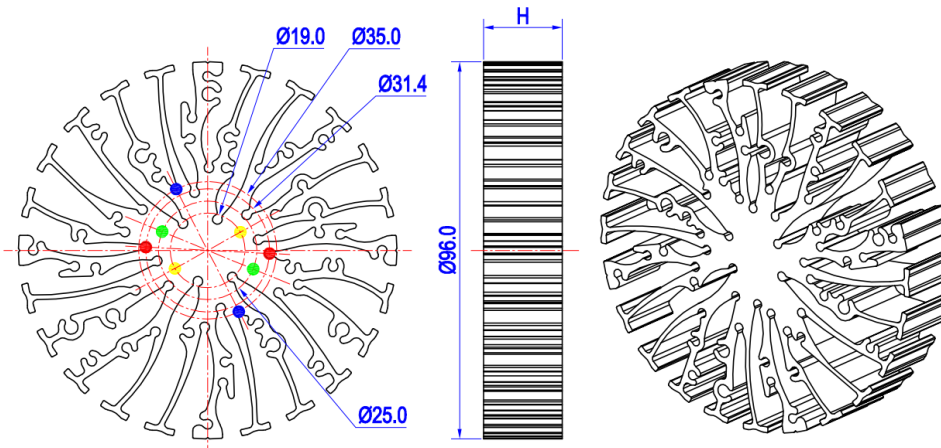
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Olivia series	Ronda series			
1	Vero 10 Vero SE 10	Bridgelux	/	/	M3	6.5mm	19.0mm/ 2-@180°
2	Vesta™ Series 9mm	BJB Holder 47.319.6180.50	/	/	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
	H6	BJB Holder 47.319.6120.50	/	/			
	H9	BJB Holder 47.319.6104.50	/	FN15xxx-xx;			
3	Vero 13 Vero SE 13	Bridgelux	FN14637-S; FN14828-M;	FN15xxx-xx;	M3	6.5mm	31.4mm/ 2-@180°
4	V15	BJB Holder 47.319.2224.50	FN14637-S	/	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
	V13	BJB Holder 47.319.2025.50		FN15xxx-xx;			



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EtraLED-BRI-9620 Bridgelux Modular Passive Star LED Heat Sink $\Phi 96\text{mm}$

The product data table

	Model No.	EtraLED-BRI-9620
	Heatsink Size	$\Phi 96 \times H20\text{mm}$
	Heatsink Material	AL6063-T5
	Finish	Black Anodized
	Weight (g)	144.0
	Dissipated power ($T_{hs-amb}, 50^\circ\text{C}$)	24.0 (W)
	Cooling surface area (mm^2)	50647
	Thermal Resistance (R_{hs-amb})	2.08 ($^\circ\text{C}/\text{W}$)

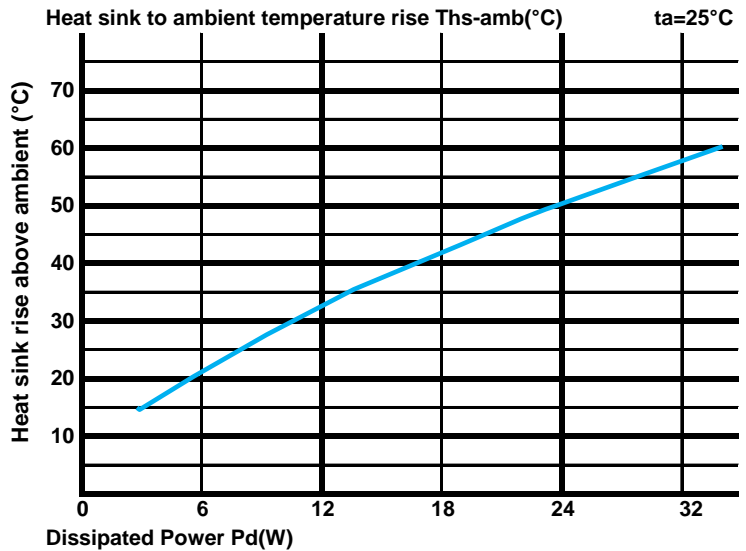
The thermal data table

* Please be aware the dissipated power P_d is not the same as the electrical power P_e of a LED module.

*To calculate the dissipated power please use the following formula: $P_d = P_e \times (1-\eta_L)$.

P_d - Dissipated power ; P_e - Electrical power ; η_L = Light efficiency of the LED module;

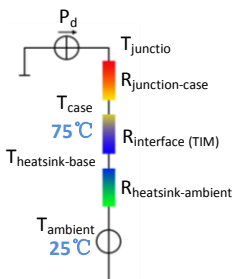
Dissipated Power P_d (W)	$P_d = P_e \times (1-\eta_L)$	Heat sink to ambient thermal resistance R_{hs-amb} ($^\circ\text{C}/\text{W}$)	Heat sink to ambient temperature rise T_{hs-amb} ($^\circ\text{C}$)
		EtraLED-BRI-9620	
6.0		3.33	20.0
12.0		2.67	32.0
18.0		2.28	41.0
24.0		2.08	50.0
32.0		1.81	58.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [$^\circ\text{C}/\text{W}$]; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [$^\circ\text{C}/\text{W}$], the thermal resistance with the heat sink is $R_{thsink-ambient}$ [$^\circ\text{C}/\text{W}$], and the ambient temperature is $T_{ambient}$ [$^\circ\text{C}$].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{thsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$